EDGE™ Solutions Module

CORNING

EDGE™ low-loss modules provide an interface between the MTP® connector on an MTP trunk and the LC duplex jumpers that connect directly to the electronics. These modules feature VFL-compatible LC shuttered adapters and are manufactured with Corning® CleanAdvantage™ Technology, an innovative factory cleaning and sealing process that minimizes debris transfer and allows you to connect with confidence.

All EDGE modules meet RoHS standards and are ideal for data center, local area network (LAN), and storage area network (SAN) applications.

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Specifications

General Specifications	
Product type	Panels and Modules
Application	Data Centre

Standards	
RoHS	Free of hazardous substances according to RoHS 2011/65/EU

Design	
Housing type	Modules

Ordering Information

Part Number	Product Description	Units Per Delivery
ECM-RM12-05-93T	12 F, LC Duplex to MTP® Connector, 50 µm multimode (OM3)	Piece
ECM-UM12-04-89G	12 F, LC Duplex to MTP® Connector, Bend-improved single-mode (OS2)	Piece
ECM-UM12-05-93Q	12 F, 50 µm (OM4), LC Duplex, MTP® PC, Connector (pinned), multimode	Piece
ECM-UM12-05-93T	12 F, 50 µm (OM3), LC Duplex, PC, MTP® PC, Connector (pinned), multimode	Piece
ECM-UM12-18-89G	12 F, LC APC to MTP® APC Connector, single-mode (OS2)	Piece

RoHS
COMPLIANT

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